

Appl. No. 09/784,234

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/784,234
Filing Date February 14, 2001
Inventor..... Nagano, S.
Assignee..... Honeywell International Inc.
Group Art Unit..... 1742
Examiner Ip, S.
Attorney's Docket No. 30-5000-(4015)-DIV1
Title: Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating Anodes,
Metal Alloys for Use as a Conductive Interconnection in an Integrated Circuit

STATEMENT OF MARK S. MATKIN

I, Mark S. Matkin, hereby state that I am the attorney who prepared the Declaration of Joint Inventors for Patent Application for execution by the inventors for U.S. Patent Application Serial No. 09/499, 025, filed November 24, 1999, which is the parent of the subject divisional application. I further state that I filed the three executed Declarations on May 2, 2000.


As the attorney responsible for preparing and filing the above identified declaration, I state that the handwritten correction appearing on page 2 of the Declaration signed by Shozo Nagano was present upon our receipt of such executed original Declaration. The correction was not entered subsequent to such receipt. Further, such correction does not alter the affirmations of the Declaration. The Declaration is in accordance with MPEP § 602.01 and is therefore valid.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of

Appl. N . 09/784,234

the United States Code and that such willful false statement may jeopardize the validity of the application or any patent issued therefrom.

Dated: 9-19-02

By: 
Mark S. Matkin
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